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	All dimensions are in mils (0.001") unless Tolerance on all dimensions shall be ±.00				
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FLE NAME: Indy_Camera_Demo.PcbDoc

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RITICAL Indy Camera Demo Critical Link, LLC 6712 Brooklawn Pkwy Syracuse, NY 13211 315.425.4045 www.criticallink.com REV: A SIZE: B NO.: 90-000133-1 PRNT NAME: 80-000322RI-1 RevA Top Assembly Drawing SCALE: SCALE: 0.98

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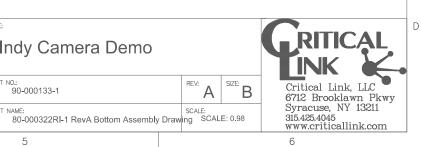
REV	DESCRIPTION	INITIALS	DATE	
А	Initial release.	0.V	11-30-10	
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Indy_Camera_Demo.PcbDoc				
Dielectric	Dielectric			
Material	Type			
Solder Resist				
FR 1	Core			

Solder Resist



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